

MA3XD11

Silicon epitaxial planar type

For high frequency rectification

■ Features

- Forward current (Average) $I_{F(AV)} = 1$ A rectification is possible
- Low forward voltage V_F

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Repetitive peak reverse voltage	V_{RRM}	25	V
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	3	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *1: Mounted on an alumina PC board

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

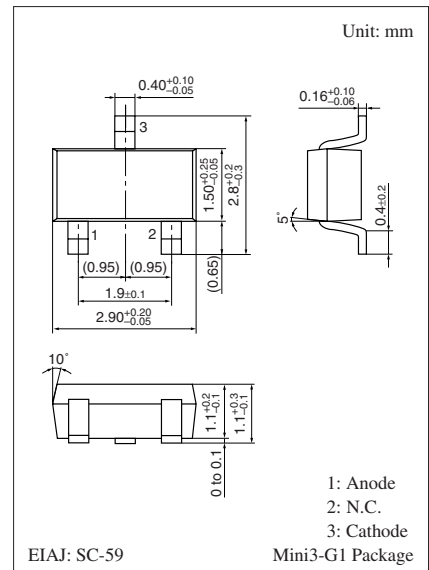
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 1.0$ A			0.45	V
Reverse current	I_R	$V_R = 20$ V			200	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		180		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

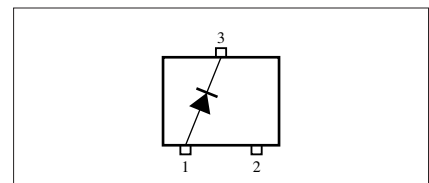
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

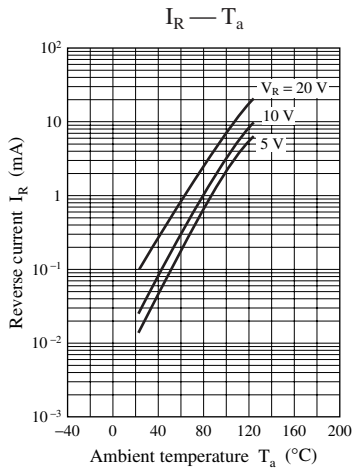
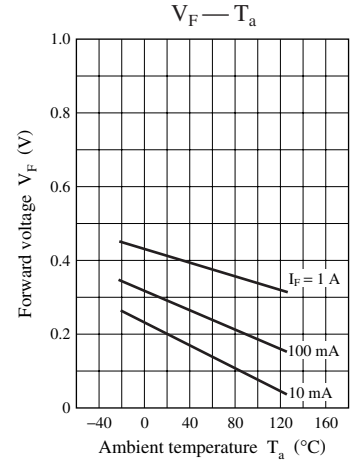
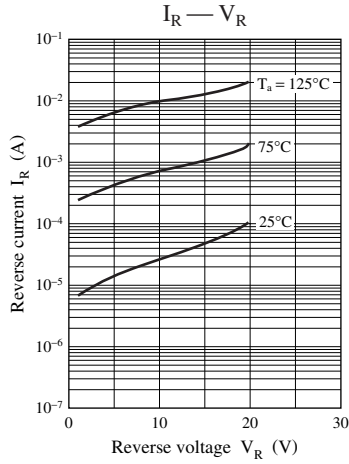
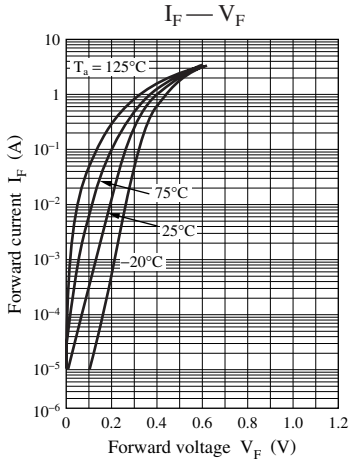
3. Absolute frequency of input and output is 400 MHz.



Marking Symbol: M6K

Internal Connection





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